

Application: (Intel Core i7-Per)

Extreme edition sequence
Intel LGA1366 Bloomfield(45nm) CPU
Core i7 940/920/950

Picture:



Thermal & Mechanical Spec.:

Thermal performance for 130W CPU
HSK Assembly Weight: 540 g (ref.)
Clipping Force: 16 Kgf (ref.)

Component Specification:

1. Heat Sink

Type: Thermal Shrink with Cu core
Material: Aluminum A6063 & Cu C1100 or Equivalent.
Dimension: 100*100*40 mm

2. Thermal interface material

Material: Dow-Corning TC-1996 or Equivalent.

3. Fan (90x20mm with Thermistor & PWM Control)

Rated Voltage: 12 V

Life Time:

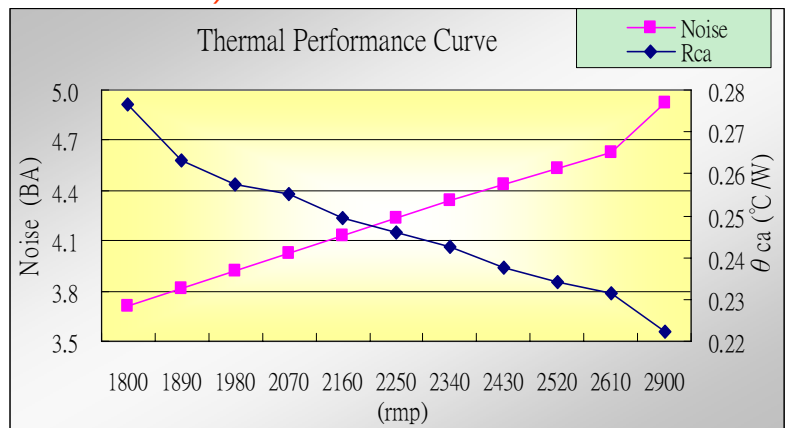
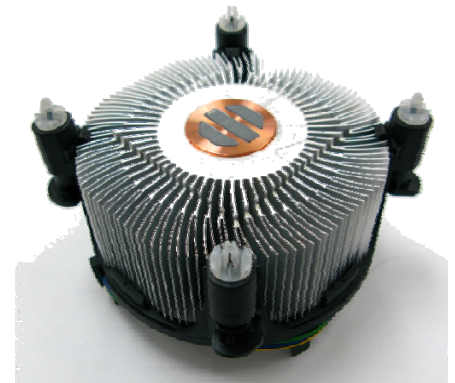
Superflo bearing 50000 hrs

Connector:

- a. Lead wire: UL 1430 AWG#26
 - pin 1: black wire-----(-)
 - pin 2: yellow wire-----(+)
 - pin 3: green wire----- (F00)
 - pin 4: blue wire----- (PWM)

b. Housing: Molex 47054-1000 or equivalent

c. Terminal: Molex 2759T 08-50-0113 or equivalent



* All readings are typical values at rated voltage.

* Specifications are subject to change without notice

Application: (Intel Core i7-Ex)

Picture:

Extreme edition sequence
Intel LGA1366 Bloomfield(45nm) CPU
Core i7 975/965



Thermal & Mechanical Spec.:

Thermal performance for 130W CPU
HSK Assembly Weight: 450 g (ref.)
Clipping Force: 20 Kgf (ref.)



Component Specification:

1. Heat Sink

Type: Stacked Fin Soldered with **Heat Column**
Material: Aluminum A1050 / C1100 or Equivalent.
Dimension: 95*95*50 mm

2. Thermal interface material

Material: Dow-Corning TC-1996 or Equivalent.

3. Fan (*90x25 mm with LED & PWM Control*)

Rated Voltage: 12 V
Life Time:

Two ball bearing 70000 hrs

4. Blue LED, and Performance/Quiet Switch



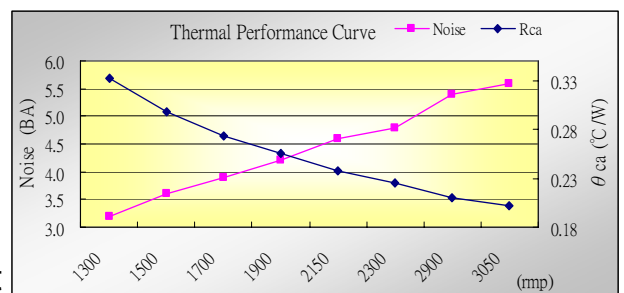
Connector:

a. Lead wire: UL 1430 AWG#26

- pin 1: black wire-----(-)
- pin 2: yellow wire-----(+)
- pin 3: green wire----- (F00)
- pin 4: blue wire----- (PWM)

b. Housing: Molex 47054-1000 or equivalent

c. Terminal: Molex 2759T 08-50-0113 or equivalent



* All readings are typical values at rated voltage.

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